



PRINTED CIRCUIT BOARDS
INTERCONNECTION CARRIERS

State of the Art: PCB's

Revisio

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01

4.11.2001

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Schematic Key for Multilayer and HDI-Technology Build-Ups

a	b	c	d	e	f	g + h + i
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04 210 FR4 35 L141.70 P12

columns and equal kind of positions are separated by "_". Equal prefixes in one column are reduced to one.

04_210_FR4_35_L141.70_p12

Layers	in μ	Material	Build-Up	Assembly	
Layer-1	35 μ	Copper		} A1 } B	
	120 μ	Prepreg			(120 μ PrePreg-Type: 2116)
	120 μ	Prepreg			
Layer-2	70 μ	Copper			
	1410 μ	L-FR4			
Layer-3	70 μ	Copper			
	120 μ	Prepreg			
	120 μ	Prepreg			
Layer-99	35 μ	Copper			

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